CMP PROCESS: OPTIMIZATION & TROUBLESHOOTING

Who should attend?

This course is designed for those individuals in the semiconductor industry who require the knowledge and skills to optimize and troubleshoot process problems on the Chemical Mechanical Polisher.

Course Benefits

Reduce time to recover from wafer processing faults.

Increase wafer processing yield.

Increase Mean Wafers Between Clean (MWBC).

Decrease number of defects per wafer.

Course Objectives

- Understand the CMP principles and applications.
- Understand the Mirra CMP baseline processes and process trends.
- Given a process recipe, make recommendations to modify process parameters to optimize the process performance for the following CMP applications:
  - ILD Planarization
  - STI
  - W plugs
  - Cu dual damascene.

Course Modules

1. *Overview*
2. *Oxide CMP*
3. *STI: Shallow Trench Isolation*
4. *Tungsten CMP*
5. *Copper CMP*
6. *Cleaner*
7. *Troubleshooting*

Registration Information

Prerequisites:

- *CMP Process: Concepts & Measurements (TRNWEB-168)*

OR

- *Mirra CMP Process: Concepts & Measurements (TRNPRC-46)*

OR

- *Mirra CMP Process: Concepts & Measurements (TRNWEB-14)*

Course Length: *4 Hours*
Course Type: *Web-based Training*
Course Number: *TRNWEB-122*

Customers: To enroll or for more information on our products and services, please call our registrar at one of the numbers below or go to *www.appliedtraining.com*.

- 1-800-468-8888, option 4 (United States)
- 1-512-272-0027 (International)

Applied Materials Employees: Please go to our intranet site, http://GTT, or call the 800 number above.

Computer System Requirements:

Attending this course requires a Windows 98, NT, 2000 or XP computer using Internet Explorer 5.5 or higher. 128MB RAM or higher and high-speed Internet access is also highly recommended.